501909360 05/03/2012

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date			
Kyoungmin PARK	05/02/2012			
Sungjin SUH	05/02/2012			

RECEIVING PARTY DATA

Name:	Pantech Co., Ltd.				
Street Address:	Pantech Bldg. R&D Center, I-2, DMC				
Internal Address:	Sangam-dong, Mapo-gu				
City:	Seoul				
State/Country:	KOREA, REPUBLIC OF				
Postal Code:	121-270				

PROPERTY NUMBERS Total: 1

Property Type	Number				
Application Number:	13505637				

CORRESPONDENCE DATA

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Correspondent Name: H.C. Park & Associates, PLC

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ATTORNEY DOCKET NUMBER: P4820US00

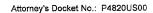
NAME OF SUBMITTER: Hae-Chan Park

Total Attachments: 2

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PATENT REEL: 028150 FRAME: 0827 TOP \$40.00 13505637

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ASSIGNMENT

Whereas, Assignor has invented certain new and useful processes, machines, articles of manufacture, compositions of matter, and/or improvements thereof ("Invention") disclosed in

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issued	□ ("Pater	•	n which	Unite	d Sta	tes Lett	ers Pate	nt, Pate	ent Nu	mber _			,	has
to:	Where	as, A	Assignor	r desi	res to	conve	y all righ	ts, titles	s, and	interes	sts in ar	nd to	the	same
				Pa Sa 12	ntech ngam 1-270		R&D Cen Mapo-gu		DMC	;				

PANTECH CO., LTD. herein further referred to as ("Assignee").

Now, for valuable consideration by Assignee to Assignor, the receipt of which is hereby acknowledged, and for other good and valuable consideration, Assignee and Assignor hereby agree as follows:

Assignor hereby conveys, assigns, sells and transfers to Assignee all rights, title and interests in and to the Invention disclosed in said application and in and to any Letters Patent of the United States (US), any continuation, division, renewal, or substitute thereof, and hereby grant to Assignee the right to apply in its own name for patents or Inventor's certificates and related rights heretofore or hereafter filed for the Invention in any and all countries, including (without limitation) all rights to claim priority based thereon, all patents granted thereon and all reissues, extensions and renewals thereof.

Assignor hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this Assignment.

Assignor further covenants that Assignee will, upon Assignee's request, be provided promptly with all pertinent facts and documents relating to the Invention, Patent, Application and any patents granted thereon, as may be known and accessible to Assignor, and Assignor will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to Assignee or Assignee's legal representative any and all papers, instruments or affidavits required to apply for, protect, obtain, maintain, issue, defend and enforce the Application, Patent, Invention, whether in the US or any and all foreign countries



and any patents granted thereon and/or for obtaining any reissue or reissues of any patent which may be granted for the invention and perform such further acts which may be necessary or desirable to carry out the intent of this agreement as the Assignee thereof shall hereafter require and prepare at assignee's expense.

IN WITNESS WHEREOF, Assignor has hereunto set hand and seal.

First Inventor's Name:	Kyoungmin PARK
Address:	Pantech Bldg. R&D Center, I-2, DMC Sangam-dong, Mapo-gu 121-270 Seoul Republic of Korea
First Inventor's Signature:	- Land Contract of the Contrac
Date:	May 2, 2012
Second Inventor's Name:	Sungjin SUH
Address:	Pantech Bldg. R&D Center, I-2, DMC Sangam-dong, Mapo-gu 121-270 Seoul Republic of Korea
Second Inventor's Signature:	
Date:	May 2, 2012
	,, <u>-,</u>